

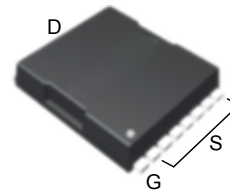
Features

- 40V/500A,
 $R_{DS(ON)} = 0.9\text{ m}\Omega$ (typ.) @ $V_{GS}=10\text{V}$
- 100% UIS + R_g Tested
- Reliable and Rugged
- Lower $R_{DS(ON)}$ to Minimize Conduction Losses
- Lead Free and Green Devices Available (RoHS Compliant)

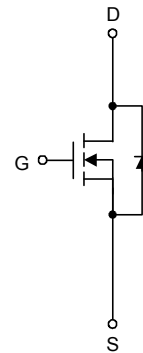
Applications

- SMPS Synchronous Rectification
- Load Switch
- DC-DC Conversion
- Or-ing

Pin Description



TOLL



N-Channel MOSFET

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter		Rating	Unit
Common Ratings				
V _{DSS}	Drain-Source Voltage		40	V
V _{GSS}	Gate-Source Voltage		±20	
T _J	Maximum Junction Temperature		175	°C
T _{STG}	Storage Temperature Range		-55 to 175	
I _S ^a	Diode Continuous Forward Current	T _C =25°C	500	A
I _D ^a	Continuous Drain Current	T _C =25°C	500	
		T _C =100°C	375	
I _{DM} ^b	Pulsed Drain Current	T _C =25°C	1500	
P _D	Maximum Power Dissipation	T _C =25°C	375	W
		T _C =100°C	187	
R _{θJC}	Thermal Resistance-Junction to Case	Steady State	0.85	°C/W
R _{θJA} ^c	Thermal Resistance-Junction to Ambient		50	°C/W
I _{AS} ^d	Avalanche Current, Single pulse	L=0.5mH	60	A
E _{AS} ^d	Avalanche Energy, Single pulse	L=0.5mH	900	mJ

Note a : Maximum continue current is limited by bonding wire.

Note b : Pulse width is limited by maximum junction temperature 175°C .

Note c : $R_{\theta JA}$ steady state $t=999\text{s}$.

Note d : UIS tested and pulse width limited by maximum junction temperature 175°C (Initial temperature $T_J=25^\circ\text{C}$).

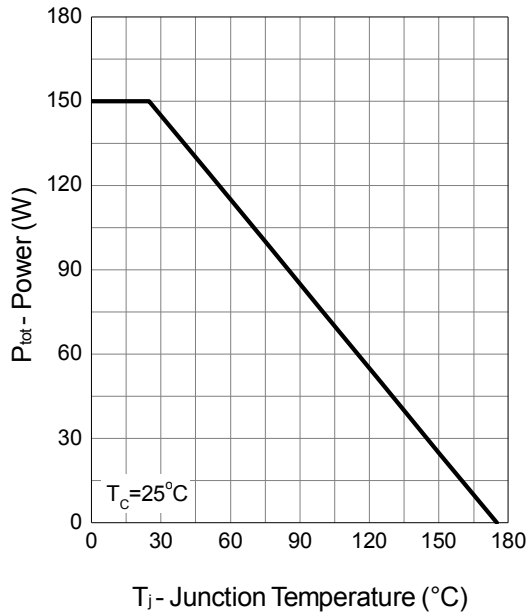
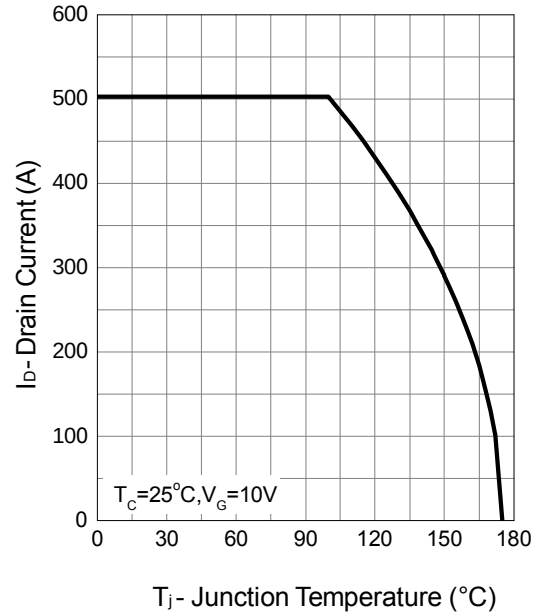
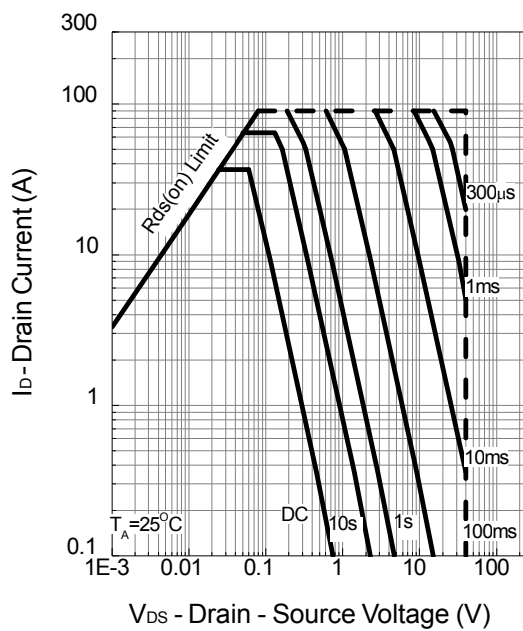
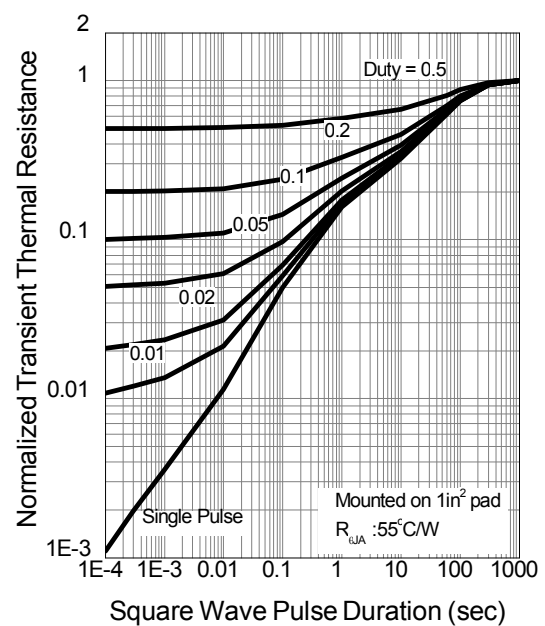
Electrical Characteristics (T_A = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250μA	40	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =32V, V _{GS} =0V T _J =85°C	- -	- -	1 30	μA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250μA	2	3	4	V
I _{GSS}	Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V		-	±100	nA
R _{DS(ON)}	Drain-Source On-state Resistance	V _{GS} =10V, I _{DS} =25A T _J =125°C	- -	0.9 1.5	1.2 -	mΩ
G _{fs}	Forward Transconductance	V _{DS} =5V, I _{DS} =20A	-	3.5	-	S
Diode Characteristics						
V _{SD} ^e	Diode Forward Voltage	I _{SD} =20A, V _{GS} =0V	-	0.78	1.1	V
t _{rr}	Reverse Recovery Time	I _{SD} =25A, dI _{SD} /dt=100A/μs V _{dd} =20V	-	61	-	ns
t _a	Charge Time		-	31	-	
t _b	Discharge Time		-	30	-	
Q _{rr}	Reverse Recovery Charge		-	67	-	nC
Dynamic Characteristics ^f						
R _G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz	0.6	0.9	2	Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =20V, Frequency=1.0MHz	-	11050	-	pF
C _{oss}	Output Capacitance		-	3000	-	
C _{rss}	Reverse Transfer Capacitance		-	380	-	
t _{d(ON)}	Turn-on Delay Time	V _{DD} =20V, R _L =20Ω, I _{DS} =1A, V _{GEN} =10V, R _G =1Ω	-	18.8	-	ns
t _r	Turn-on Rise Time		-	9.8	-	
t _{d(OFF)}	Turn-off Delay Time		-	50	-	
t _f	Turn-off Fall Time		-	90.8	-	
Gate Charge Characteristics ^f						
Q _g	Total Gate Charge	V _{DS} =20V, V _{GS} =10V, I _{DS} =25A	-	88.98	-	nC
Q _{gth}	Threshold Gate Charge		-	15.84	-	
Q _{gs}	Gate-Source Charge		-	24.75	-	
Q _{gd}	Gate-Drain Charge		-	15.63	-	

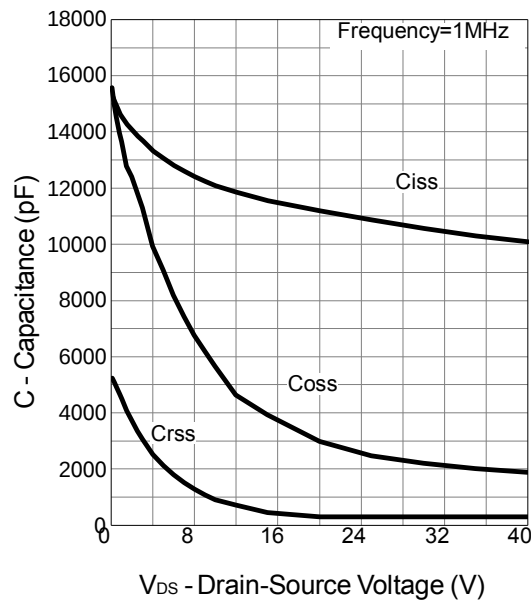
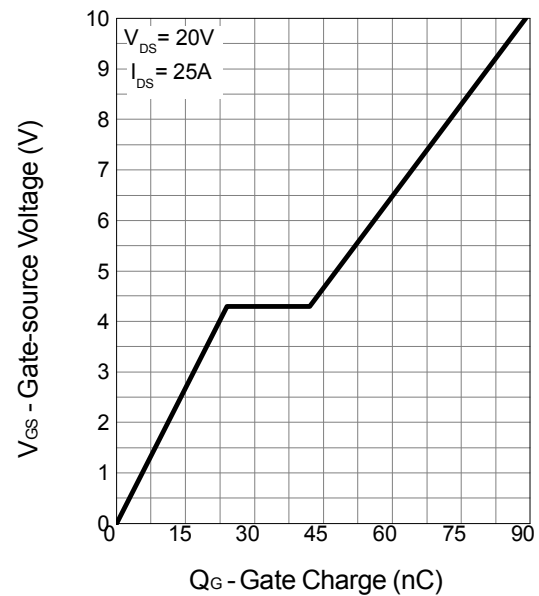
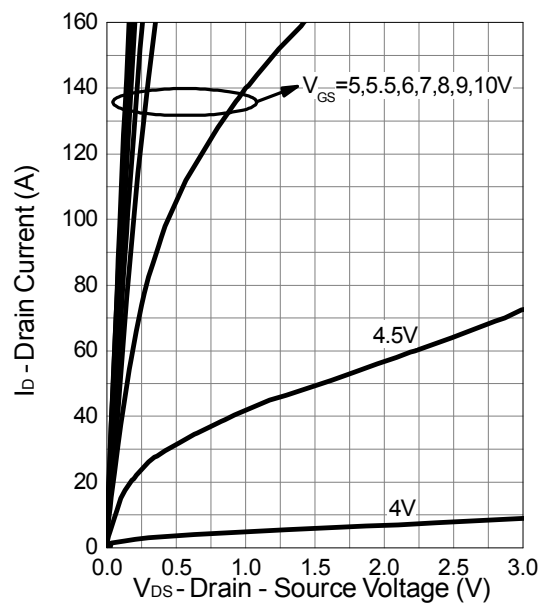
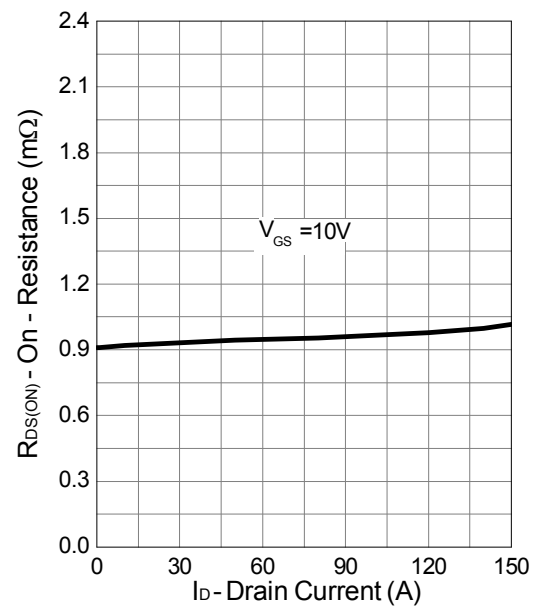
Note e^e Pulse test ; pulse width≤300μs, duty cycle≤2%.

Note f^f Guaranteed by design, not subject to production testing.

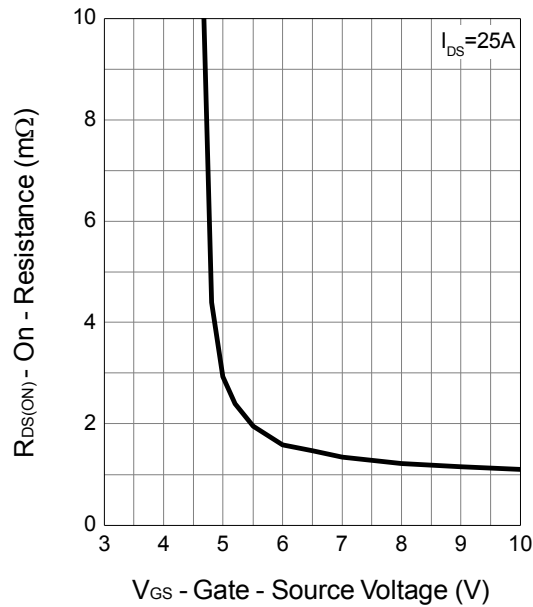
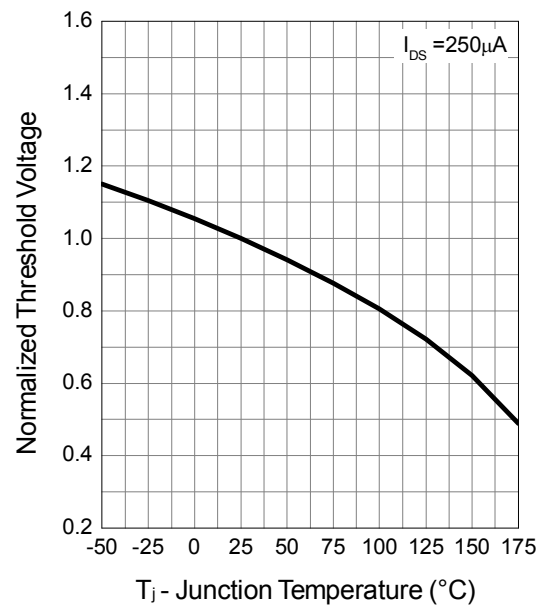
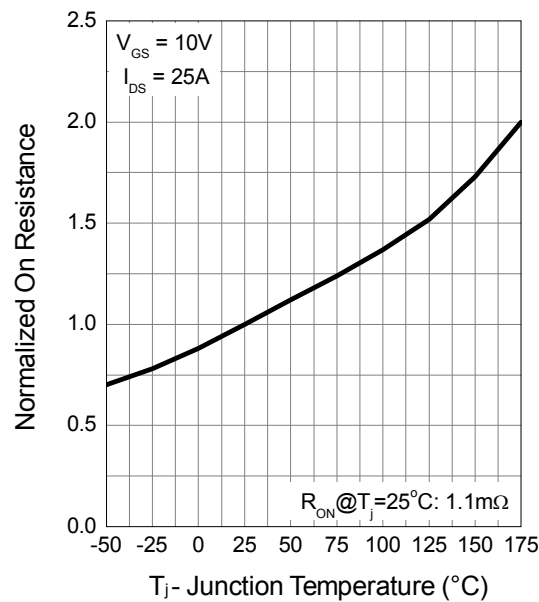
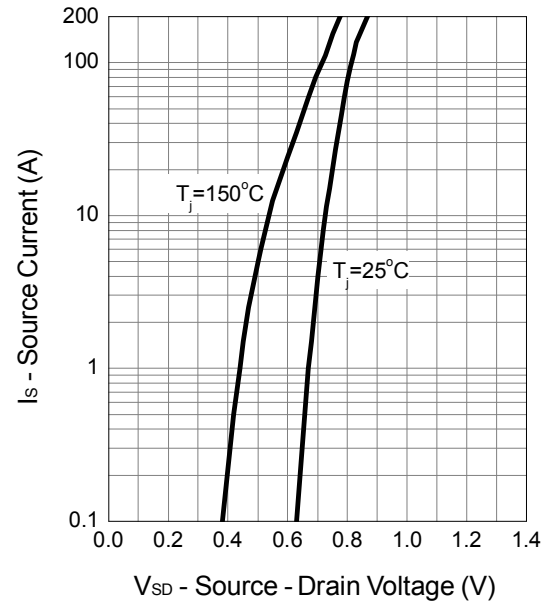
Typical Operating Characteristics

Power Dissipation

Drain Current

Safe Operation Area

Thermal Transient Impedance


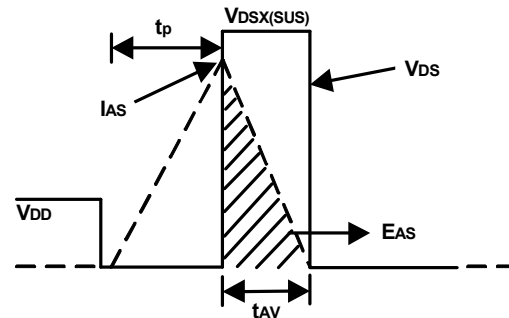
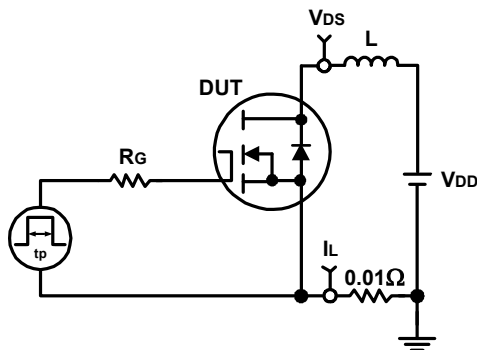
Typical Operating Characteristics (Cont.)

Capacitance

Gate Charge

Output Characteristics

Drain-Source On Resistance


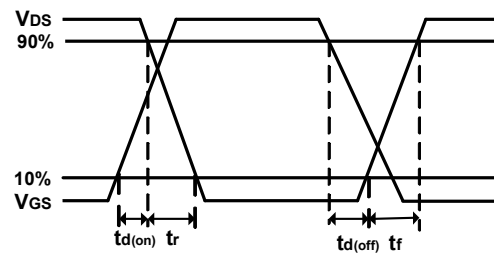
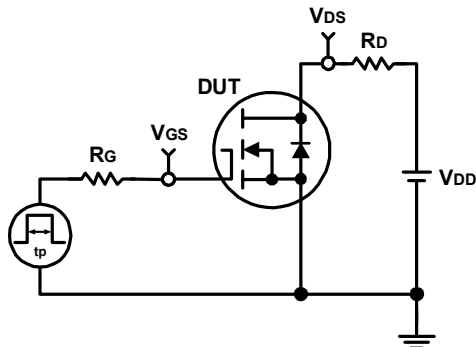
Typical Operating Characteristics (Cont.)

Gate-Source On Resistance

Gate Threshold Voltage

Drain-Source On Resistance

Source-Drain Diode Forward


Avalanche Test Circuit and Waveforms

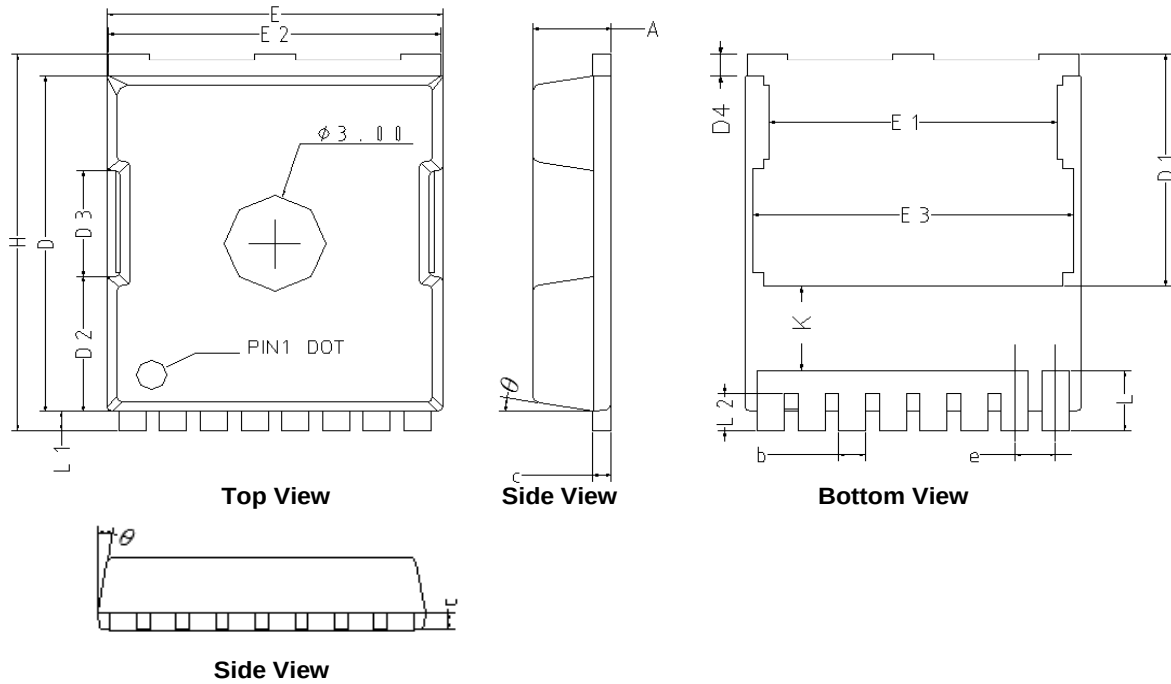


Switching Time Test Circuit and Waveforms



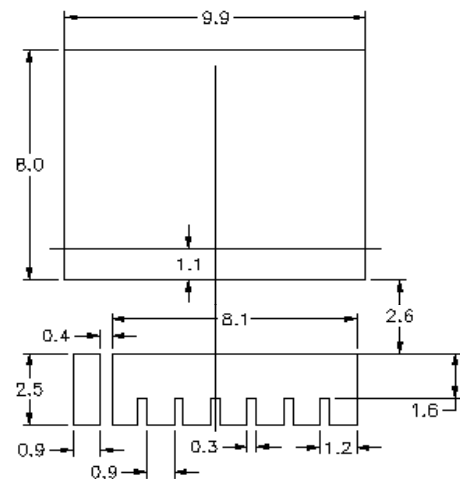
Package Information

TOLL



SYMBOLS	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	2.20	2.40	0.087	0.094
b	0.70	0.90	0.028	0.035
c	0.40	0.60	0.016	0.024
D	10.23	10.63	0.403	0.419
D1	7.05	7.45	0.278	0.293
D2	3.98	4.38	0.157	0.172
D3	3.10	3.50	0.122	0.138
D4	0.50	0.90	0.020	0.035
E	9.70	10.10	0.382	0.398
E1	8.30	8.70	0.327	0.343
E2	9.60	10.00	0.378	0.394
E3	9.26	9.66	0.365	0.380
H	11.53	11.93	0.454	0.470
e	1.2 BSC		0.0472 BSC	
K	2.43	2.83	0.096	0.111
L	1.65	2.05	0.065	0.081
L1	0.40	0.80	0.016	0.031
L2	0.95	1.35	0.037	0.053
θ	6°	10°	6°	10°

RECOMMENDED LAND PATTERN



UNIT: mm